PRODUCT DATA SHEET

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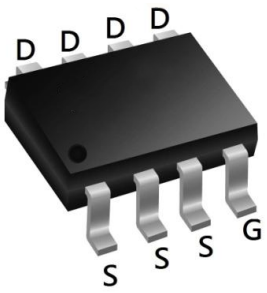
Datasheet Resources Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

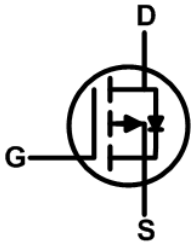
AO4455

N-Ch 20V Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



SOP8



Absolute Maximum Ratings (T_A= 25°C, unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source voltage		V_{DS}	-30	V
Gate-Source voltage		V_{GS}	±20	V
Continuous Drain Current	T_A=25°C	I_D	-18	A
	T_A=100°C		-8.8	
Pulsed Drain Current[1]		I_{DM}	-53	A
Single Pulse Avalanche Energy[2]		EAS	80	mJ
Total Power Dissipation	T_A=25°C	P_D	3	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient[3]	$R_{\theta JA}$	41.6	°C/W

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	V_{GS} = 0V, I_D = -250μA	-30	-	-	V
Gate-body Leakage current		I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T_J=25°C	I_{DSS}	V_{DS} = -30V, V_{GS} = 0V	-	-	-1	μA
	T_J=100°C			-	-	-100	
Gate-Threshold Voltage		$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = -250μA	-1.0	-	-2.5	V
Drain-Source On-Resistance[4]		$R_{DS(on)}$	V_{GS} = -10V, I_D = -12A	-	5.8	9.2	mΩ
			V_{GS} = -4.5V, I_D = -10A	-	8	14	
Forward Transconductance[4]		g_{fs}	V_{DS} = -10V, I_D = -10A	-	50	-	S
Dynamic Characteristics[5]							
Input Capacitance		C_{iss}	V_{DS} = -15V, V_{GS} =0V, f =1MHz	-	3100	-	pF
Output Capacitance		C_{oss}		-	430	-	
Reverse Transfer Capacitance		C_{rss}		-	358	-	
Gate Resistance		R_g	f=1MHz	-	9.5	-	Ω
Switching Characteristics[5]							
Total Gate Charge		Q_g	V_{GS} = -10V, V_{DS} = -15V I_D= -12A	-	35	-	nC
Gate-Source Charge		Q_{gs}		-	9.9	-	
Gate-Drain Charge		Q_{gd}		-	10.5	-	
Turn-On Delay Time		$t_{d(on)}$	V_{GS} =-10V, V_{DD} = -15V R_G = 3Ω, I_D= -12A	-	10.8	-	ns
Rise Time		t_r		-	13.2	-	
Turn-Off Delay Time		$t_{d(off)}$		-	73	-	
Fall Time		t_f		-	35	-	
Reverse Recovery Time		t_{rr}	I_F = -12A, dI_F/dt = 100A/μs	-	25	-	ns
Reverse Recovery Charge		Q_{rr}		-	10	-	nC
Drain-source body diode Characteristics							
Diode Forward Voltage[4]		V_{SD}	I_S = -1A, V_{GS} = 0V	-	-	-1.2	V
Continuous Source Current	T_A=25°C	I_S	-	-	-	-14	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C.
2. The EAS data shows Max. rating . The test condition is V_{DD}= -25V, V_{GS}= -10V, L=0.1mH, I_{AS}= -40A.
3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

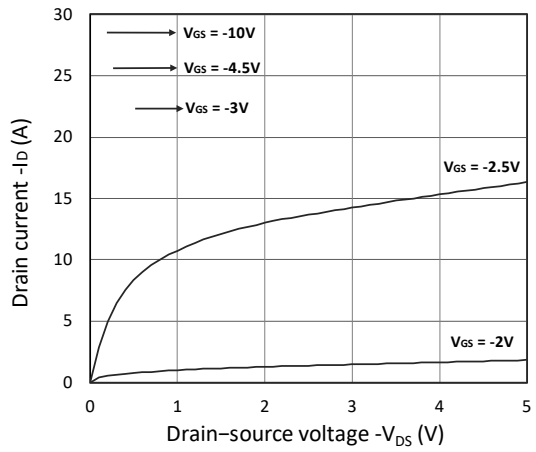


Figure 1. Output Characteristics

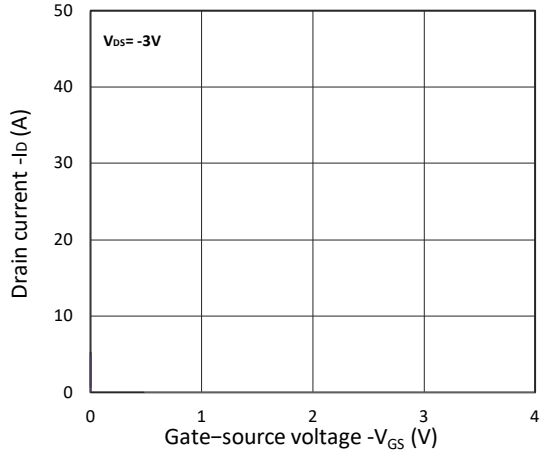


Figure 2. Transfer Characteristics

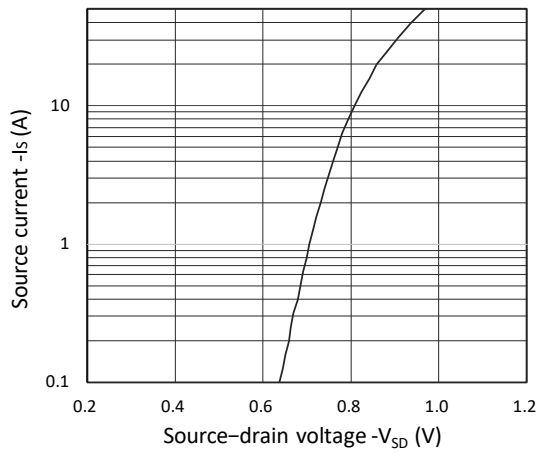


Figure 3. Forward Characteristics of Reverse

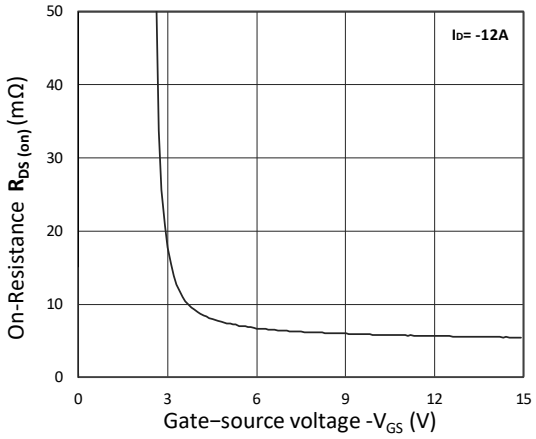


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

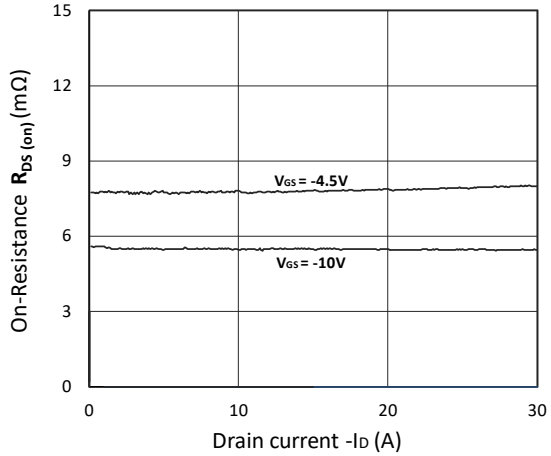


Figure 5. $R_{DS(ON)}$ vs. I_D

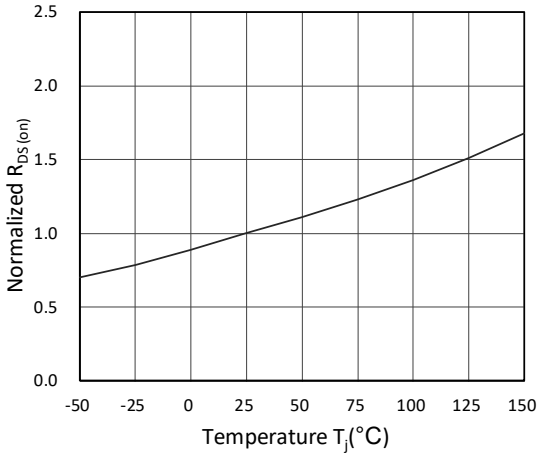


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

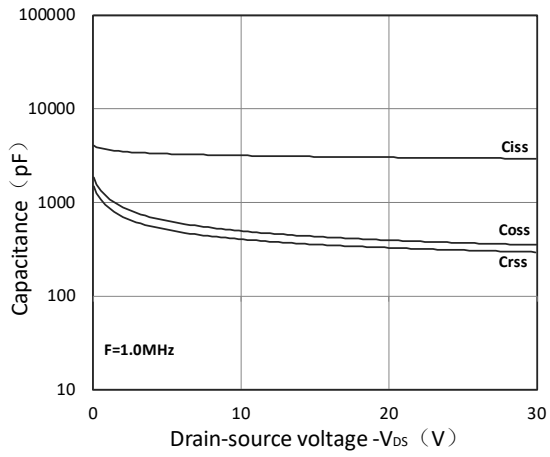


Figure 7. Capacitance Characteristics

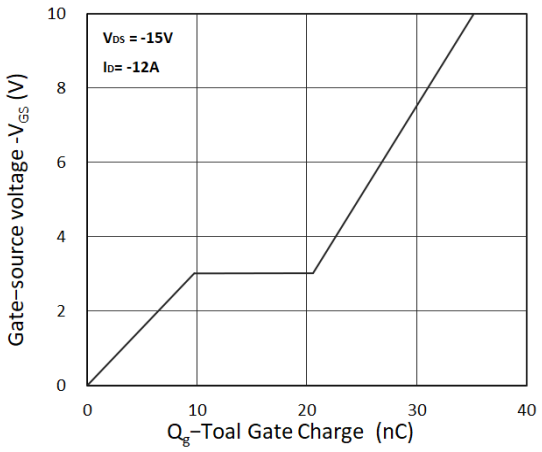


Figure 8. Gate Charge Characteristics

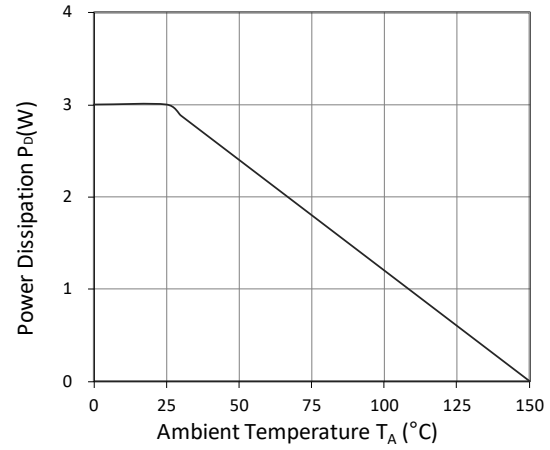


Figure 9. Power Dissipation

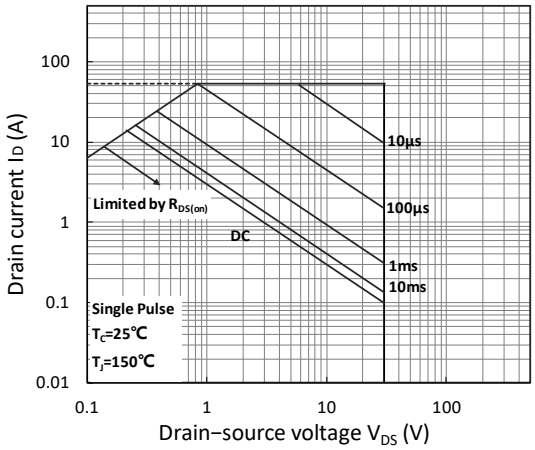


Figure10. Safe Operating Area

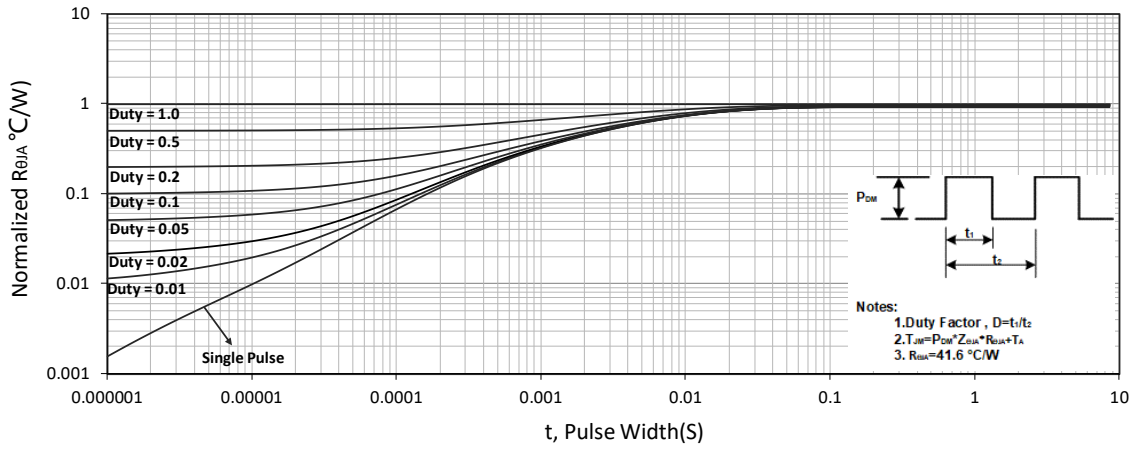
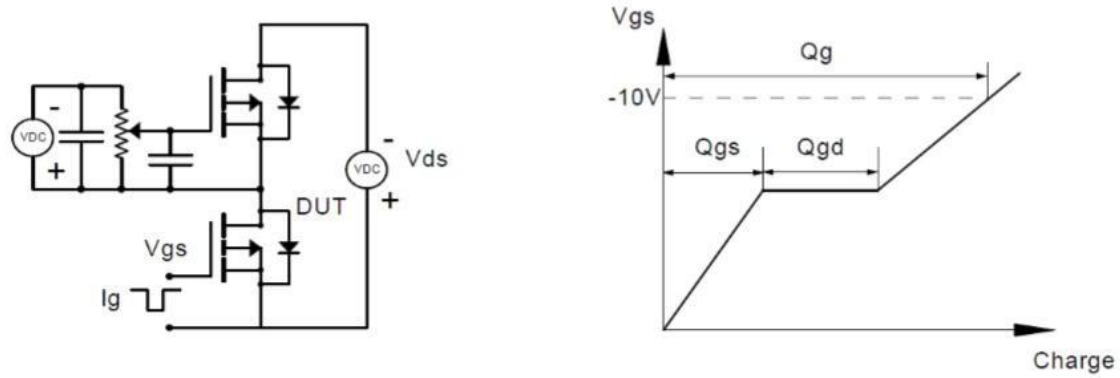


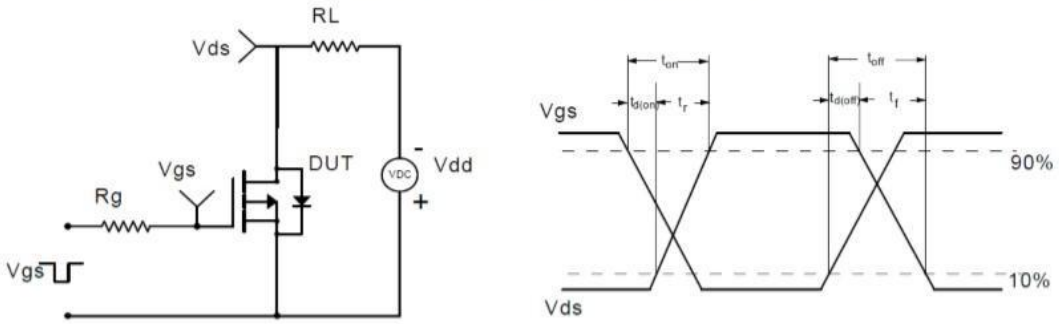
Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

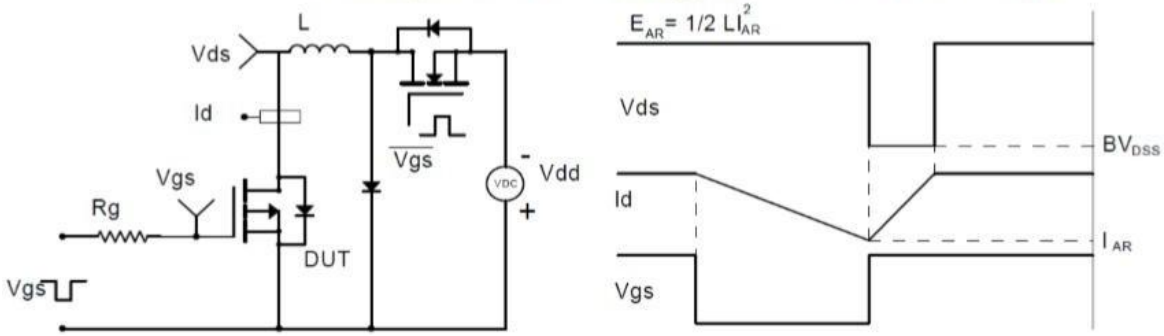
Gate Charge Test Circuit & Waveform



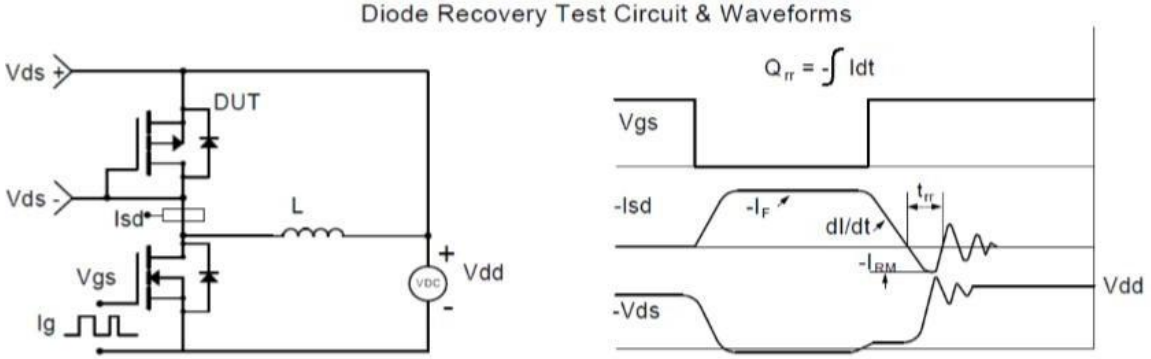
Resistive Switching Test Circuit & Waveforms



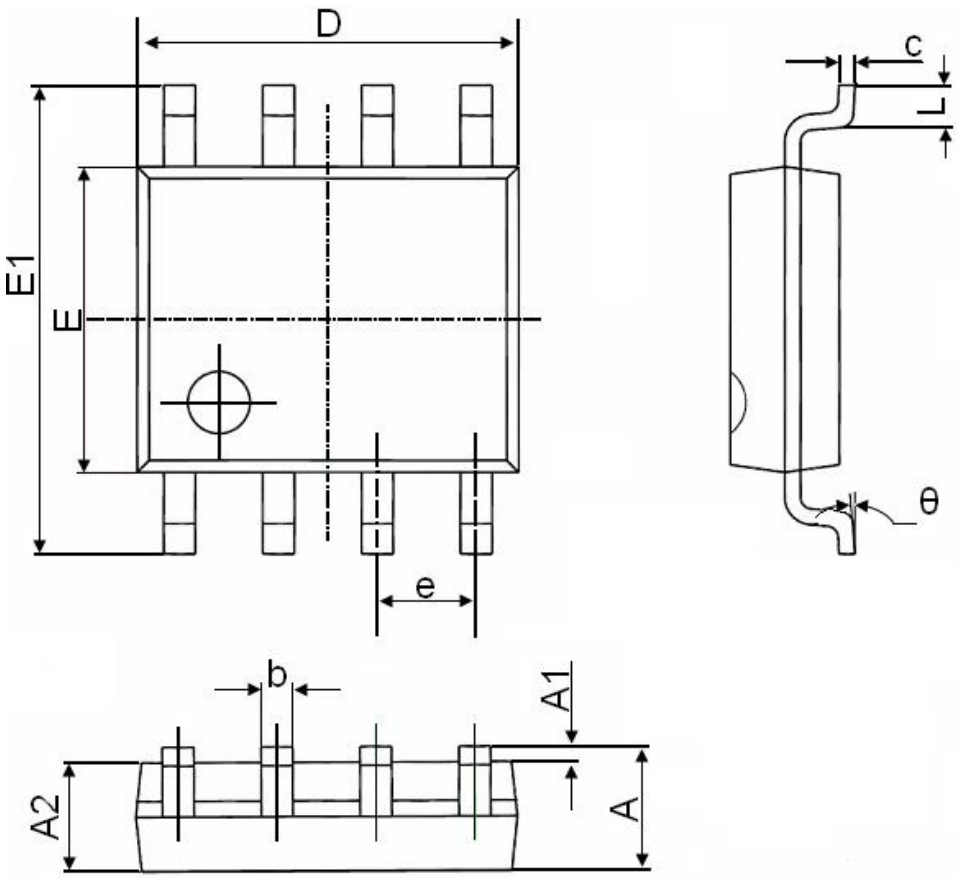
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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